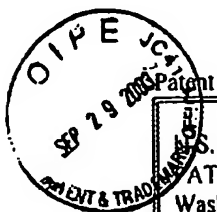


9-29-03



Attorney Docket No. MTI-31607

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Washington, D.C. 20231 SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANT (SEPT. - 2003)	ATTY. DOCKET NO.	Serial No.
	MTI-31607	10/050,507
	Applicant	Confirmation No.
	Lee, Teck Kheng	7687
	Filing Date	Group Art Unit
	January 16, 2002	2813

U.S. PATENT DOCUMENTS

Examiner Initials	Patent Number	Issue Date	Patentee	U.S. Class	Sub-Class	Filing Date
CAT	5,148,265	09/15/92	Khandros			
CAT	5,346,861	09/13/94	Khandros			
CAT	5,347,159	09/13/94	Khandros			
CAT	5,679,977	10/21/97	Khandros			
CAT	5,683,942	11/04/97	Kata			
CAT	5,777,391	07/07/98	Nakamura			
CAT	5,905,303	05/18/99	Kata			
CAT	6,217,343	04/17/01	Okuno			

FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATION

Examiner Initials	Document Number	Publication Date	Country	Int'l Class	Sub-Class	Translation (Yes/No)
CAT	EP684644	11/29/95	EPO			
CAT	EP1009027	06/14/00	EPO			
CAT	KR 2001054744	07/02/01	Korea			English Abstract

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

Examiner Initials	Non-Patent Document

Examiner Initials	<i>Cat 9-22</i>	Date Considered	<i>4-2-03</i>
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.			

4-25-03



U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE
Washington, D.C. 20231

**SUPPLEMENTAL
INFORMATION DISCLOSURE
STATEMENT BY APPLICANT
(04-2003)**

ATTY. DOCKET NO.

MTI-31607

Applicant

Lee, Teck Kheng

Filing Date

01-16-02

Serial No.

10/050,507

Confirmation No.

7687

Group Art Unit

2813

U.S. PATENT DOCUMENTS

Examiner Initial	Patent Number	Issue Date	Patentee	U.S. Class	Sub-Class	Filing Date

PUBLISHED U.S. PATENT APPLICATIONS

Examiner Initial	Publ. Number	Publ. Date	Applicant	U.S. Class	Sub-Class	Filing Date
CA	US 2002/0142513	Oct. 3, 2002	Fee et al.	438	106	Apr. 19, 2001

FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATION

Examiner Initial	Document Number	Publication Date	Country	Int'l Class	Sub-Class	Translation (Yes/No)

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

Examiner Initial	Non-Patent Document

Examiner Initials	<i>Chen A 20</i>	Date Considered	<i>4-25</i>
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.			

3-12-02

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Washington, D.C. 20231 INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO.	Serial No.
	MTI-31607	10/050,507
	Applicant	Confirmation No.
	Lee, Teck Kheng	7687
	Filing Date	Group Art Unit
	01-16-02	2812

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		Patent Number	Issue Date	Patentee	U.S. Class	Sub-Class	Filing Date
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CAT	A2	6,048,755	04-11-00	Jiang et al.	438	118	11-12-98
CAT	A3	6,177,723	01-23-01	Eng et al.	257	691	12-17-97
CAT	A4	6,222,265	04-24-01	Akram et al.	257	723	12-17-99
CAT	A5	6,232,666	05-15-01	Corisis et al.	257	774	12-04-98
CAT	A6	6,242,932	06-05-01	Hembree	324	755	02-19-99
CAT	A7	6,265,775	07-24-01	Seyyedy	257	737	09-08-99
CAT	A8	6,291,265	09-18-01	Mess	438	107	02-09-00
CAT	A9	6,295,730	10-02-01	Akram	29	843	09-02-99

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Examiner Initial	Document Number	Publication Date	Country	Int'l Class	Sub-Class	Translation (Yes/No)
B1						

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

Examiner Initial	Non-Patent Document
C1	

Examiner Initials <u>Craig A. Z...</u>	Date Considered <u>4-4-5</u>
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

2-8-05

Patent

Attorney Docket No. MTI-31607

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Washington, D.C. 20231 SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANT (February 8, 2005)	ATTY. DOCKET NO.	Serial No.
	MTI-31607	10/050,507
	Applicant	Confirmation No.
	Lee, Teck Kheng	7687
	Filing Date	Group Art Unit
	January 16, 2002	2813

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Examiner Initials	Patent Number	Publication Date	Patentee or Applicant	U.S. Class	Sub-Class
CAT	5,723,347	03/1998	Hirano et al.	RECEIVED FEB 08 2005 OFFICE OF PETITIONS	
CAT	5,812,378	09/1998	Fjelstad et al.		
CAT	5,892,271	04/1999	Takeda et al.		
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CAT	6,271,469	08/2001	Ma et al.		
CAT	6,291,884	09/2001	Glenn et al.		
CAT	6,376,769	04/2002	Chung		
CAT	6,404,648	06/2002	Slupe et al.		
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CAT	2001/053563	12/2001	Kim et al.		
CAT	2003/0042595	03/2003	Canella		

Examiner Initials	Date Considered
CAT	4-4-5
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

2-8-05

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Attorney Docket No. MTI-31607

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	January 16, 2002	2813

Examiner Initials	Patent Number	Publication Date	Patentee or Applicant	U.S. Class	Sub-Class
CAT	2004/0026773	02/2004	Koon et al.	RECEIVED FEB 08 2005	
CAT	2004/0212055	10/2004	Exposito et al.		
CAT	2004/0217454	11/2004	Brechignav et al.	OFFICE OF PETITIONS	

FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATION

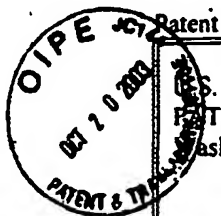
Examiner Initials	Document Number	Publication Date	Country	Name of Patentee or Applicant	Translation (Yes/No)
CAT	JP 04030456	02/1992	Japan	Yamaguchi	Yes (Abstract)
CAT	EP 0475022 A1	03/1992	EPO	Grube et al.	
CAT	EP 0997942 A2	05/2000	EPO	Horiuchi et al.	
CAT	JP 02000230964	08/2000	Japan	Hikita	Yes (Abstract)

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

Examiner Initials	Non-Patent Document
CAT	Australian Search Report dated 11 Aug 2004 (3 pages).
CAT	Australian Search Report dated 16 Aug 2004 (4 pages).

Examiner Initials <i>Craig A. Jell</i>	Date Considered <i>4-4-5</i>
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

10-20-03



Attorney Docket No. MTI-31607

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Washington, D.C. 20231 SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT BY APPLICANT (OCT 2003)	ATTY. DOCKET NO.	Serial No.
	MTI-31607	10/050,507
	Applicant	Confirmation No.
	Lee, Teck Kheng	7687
	Filing Date	Group Art Unit
	January 16, 2002	2813

U.S. PATENT DOCUMENTS

Examiner Initials	Patent Number	Issue Date	Patentee	U.S. Class	Sub- Class	Filing Date
CA	6,413,102	July 2, 2002	Jiang et al.	439	70	Dec.22, 1999

FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATION

Examiner Initials	Document Number	Publication Date	Country	Int'l Class	Sub- Class	Translation (Yes/No)

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

Examiner Initials	Non-Patent Document

Examiner Initials	<i>Chen A-20</i>	Date Considered	<i>4-4-5</i>
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.			

Patent

Attorney Docket No. MTI-31607

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313 INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO.	Serial No.
	MTI-31607	10/050,507
	Applicant	Confirmation No.
	Teck Kheng Lee	7687
	Filing Date	Group Art Unit
	January 16, 2002	2813

FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATION

Examiner Initial		Document Number	Publication Date	Country	Int'l Class	Sub-Class	Translation (Yes/No)
CAT	A1	2000-183082	06-30-00	JP	H01L	21/566	Abstract
CAT	A2	2001077294	03-23-01	JP	H01L	25/065	Yes
CAT	A3	99/65282	12-16-99	WO	H05K	1/11	N/A

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

Examiner Initial		Non-Patent Document
CAT	B1	Copy of Australian Patent Office, Search Report, 30 May 2003, 4 pages.
CAT	B2	Al-sarawi, S. et al., "A Review of 3-D Packaging Technology," <i>Components, Packaging, and Manufacturing Technology, Part B: IEEE Transactions on Advanced Packaging</i> , Vol 21, Issue 1, Feb. 1998, pp. 2-14.
CAT	B3	Andros, F. et al., "TBOA Package Technology," <i>Components, Packaging, and Manufacturing Technology, Part B: IEEE Transactions on Advanced Packaging</i> , Vol. 17, Issue 4, Nov. 1994; pp. 564-568.
CAT	B4	Clot, Ph. et al., "Flip-Chip on Flex for 3D Packaging," 1999. 24 th IEEE/CPMT, 18-19 Oct. 1999; pp. 36-41.
CAT	B5	Ferrando, F. et al., "Industrial Approach of a Flip-Chip Method Using the Stud-Bumps With a Non-Conductive Paste," <i>Adhesive Joining and Coating Technology in Electronics Manufacturing</i> , 2000. Proceedings. 6 th International Conference on, 18-21, June 2000, pp. 205-211.
CAT	B6	Gallagher, C. et al., "A Fully Additive, Polymeric Process for the Fabrication and Assembly of Substrate and Component Level Packaging," <i>The First IEEE International Symposium on Polymeric Electronics Packaging</i> , 26-30, Oct. 1997, pp. 56-63.
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CAT	B9	Haug, R. et al., "Low-Cost Direct Chip Attach: Comparison of SMD Compatible FC Soldering with Anisotropically Conductive Adhesive FC Bonding," <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , Vol. 23, No. 1, Jan 2000, pp. 12-18.

Examiner Initials	Max G. 20	Date Considered	4-4-3
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.			

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1 of 2

09-04-2004

Patent

Amey Docket No. MTI-31607

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313 INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO.	Serial No.
	MTI-31607	10/050,507
	Applicant	Confirmation No.
	Tock Kheng Lee	7687
	Filing Date	Group Art Unit
	January 16, 2002	2813

Examiner Initial		Non-Patent Document
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LAT	B15	Too, Y. et al., "Enhancing Moisture Resistance of FBGA," Electronic Components and Technology Conference, 1998, 48th IEEE, 25-28 May 1998, pp. 930-935.
LAT	B16	Teutsch, T. et al., "Wafer Level CSP using Low Cost Electroless Redistribution Layer," Electronic Components and Technology Conference, 2000, 2000 Proceedings, 50th, 21-24 May 2000, pp. Pages: 107-113.
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LAT	B18	Tsu, C. et al. "Pad Distribution Technology for Flip Chip Applications", 1998 Electronic Components and Technology Conference, pp. 1098-1102
LAT	B19	Xiao, G. et al., "Reliability Study and Failure Analysis of Fine Pitch Solder-Bumped Flip Chip on Low-Cost Flexible Substrate Without Using Stiffener," IEEE, 2002, Proceedings 52nd, 28-31 May 2002, pp. 112-118.

Examiner Initials	Chris A. J. R.	Date Considered	4-4-5
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.			

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09-09-2004

Patent

Attorney Docket No. MTI-31607

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313 INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO.	Serial No.
	MTI-31607	10/050,507
	Applicant	Confirmation No.
	Teck Kheng Lee	7687
Filing Date		Group Art Unit
January 16, 2002		2813

U.S. PATENT DOCUMENTS

Examiner Initial		Document No.	Publication/ Issue Date	Patentee	U.S. Class	Sub-Class
CAI	A1	3,239,496	03/1966	Jursich		
CAI	A2	4,074,342	02/1978	Horn et al.		
CAI	A3	4,807,021	02/1989	Okumura		
CAI	A4	4,818,728	04/1989	Rai et al.		
CAI	A5	5,366,794	11/1994	Nakao		
CAI	A6	5,385,869	01/1995	Lin et al.		
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CAI	A9	5,404,044	04/1995	Booth et al.		
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CAI	A11	5,422,205	06/1995	Inoue et al.		
CAI	A12	5,438,477	08/1995	Pasch		
CAI	A13	5,448,511	09/1995	Paurus et al.		
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CAI	A16	5,504,277	04/1996	Danner		
CAI	A17	5,598,033	01/1997	Behlen et al.		
CAI	A18	5,648,446	07/1997	Nicewarner, Jr. et al.		
CAI	A19	5,663,530	09/1997	Schueler et al.		
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CAI	A21	5,674,785	10/1997	Akram et al.		
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CAI	A23	5,719,449	02/1998	Strauss		
CAI	A24	5,721,151	02/1998	Padmanabham et al.		
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CAI	A30	5,798,283	08/1998	Bentlage et al.		
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CAI	A32	5,805,422	09/1998	Otake et al.		
CAI	A33	5,818,113	10/1998	Izaki et al.		
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Examiner Initials	CAI 9-20	Date Considered	4-4-5
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.			

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1 of 4

SEPT. 20, 2004

Patent

Attorney Docket No. MTI-31607

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313 INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO.	Serial No.
	MTI-31607	10050,507
	Applicant	Confirmation No.
	Tock Kheng Lee	7687
	Filing Date	Group Art Unit
	January 16, 2002	2813

Examiner Initial	Document No.	Publication/ Issue Date	Patentee	U.S. Class	Sub-Class
AT	A35	5,834,338	11/1998	Takeda et al.	
AT	A36	5,834,366	11/1998	Akram	
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AT	A39	5,843,808	12/1998	Kamezuo	
AT	A40	5,844,168	12/1998	Schmeller et al.	
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AT	A65	6,057,178	05/2000	Galuschki et al.	
AT	A66	6,060,782	05/2000	Ohsono et al.	
AT	A67	6,064,114	05/2000	Higgins, III	
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Examiner Initials	Date Considered
AT 9-22	9-22
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	

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Patent

Attorney Docket No. MTI-31607

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313 INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO.	Serial No.
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	Teck Kheng Lee	7687
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Examiner Initial	Document No.	Publication/ Issue Date	Patentee	U.S. Class	Sub- Class
CAI	A71	6,079,991	Lenke et al.		
CAI	A72	6,093,035	Lenke et al.		
CAI	A73	6,116,921	Scholtz et al.		
CAI	A74	6,124,631	Cordot et al.		
CAI	A75	6,127,736	Akron		
CAI	A76	6,133,637	Hikita et al.		
CAI	A77	6,137,062	Zimmerman		
CAI	A78	6,137,164	Yew et al.		
CAI	A79	6,137,183	Sako		
CAI	A80	6,157,541	Hacke		
CAI	A81	6,163,885	Gaynes et al.		
CAI	A82	6,172,422 B1	Chigawa et al.		
CAI	A83	6,179,598 B1	Brand		
CAI	A84	6,191,487 B1	Rodenbeck et al.		
CAI	A85	6,208,521 B1	Nakatsuka		
CAI	A86	6,212,768 B1	Murakami		
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CAI	A88	6,218,202 B1	Yew et al.		
CAI	A89	6,219,911 B1	Estes et al.		
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CAI	A99	6,338,985	Greenwood		
CAI	A100	6,429,516 B1	Tsumoi		
CAI	A101	6,432,737 B1	Webster		
CAI	A102	6,468,831	Leong et al.		
CAI	A103	6,482,676	Tsumoi et al.		
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Patent

Attorney Docket No. MTI-31607

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE Alexandria, VA 22313 INFORMATION DISCLOSURE STATEMENT BY APPLICANT	ATTY. DOCKET NO.	Serial No.
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	Tock Khing Lee	7687
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Examiner Initial		Document No.	Publication/ Issue Date	Patentee	U.S. Class	Sub- Class
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